High Power Infrared Emitting Diode, 940 nm, GaAlAs, MQW

DESCRIPTION
VSML3710 is an infrared, 940 nm emitting diode in GaAlAs, MQW (multi quantum well) technology with high radiant power, molded in a PLCC-2 package for surface mounting (SMD).

FEATURES
• Package type: surface mount
• Package form: PLCC-2
• Dimensions (L x W x H in mm): 3.5 x 2.8 x 1.75
• Peak wavelength: \( \lambda_p = 940 \text{ nm} \)
• High reliability
• High radiant power
• High radiant intensity
• Angle of half intensity: \( \varphi = \pm 60^\circ \)
• Low forward voltage
• Suitable for high pulse current operation
• Good spectral matching with Si photodetectors
• Package matched with IR emitter series VEMT3700
• Floor life: 168 h, MSL 3, acc. J-STD-020
• Lead (Pb)-free reflow soldering
• AEC-Q101 qualified
• Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS
• IR emitter in photointerrupters, sensors, and reflective sensors
• IR emitter in low space applications
• Household appliance
• Tactile keyboards

PRODUCT SUMMARY

<table>
<thead>
<tr>
<th>COMPONENT</th>
<th>( I_e ) (mW/sr)</th>
<th>( \varphi ) (deg)</th>
<th>( \lambda_p ) (nm)</th>
<th>( t_r ) (ns)</th>
</tr>
</thead>
<tbody>
<tr>
<td>VSML3710</td>
<td>9.5</td>
<td>( \pm 60 )</td>
<td>940</td>
<td>15</td>
</tr>
</tbody>
</table>

Note
• Test conditions see table “Basic Characteristics”

ORDERING INFORMATION

<table>
<thead>
<tr>
<th>ORDERING CODE</th>
<th>PACKAGING</th>
<th>REMARKS</th>
<th>PACKAGE FORM</th>
</tr>
</thead>
<tbody>
<tr>
<td>VSML3710-GS08</td>
<td>Tape and reel</td>
<td>MOQ: 7500 pcs, 1500 pcs/reel</td>
<td>PLCC-2</td>
</tr>
<tr>
<td>VSML3710-GS18</td>
<td>Tape and reel</td>
<td>MOQ: 8000 pcs, 8000 pcs/reel</td>
<td>PLCC-2</td>
</tr>
</tbody>
</table>

Note
• MOQ: minimum order quantity
**ABSOLUTE MAXIMUM RATINGS** (\(T_{\text{amb}} = 25 \, ^\circ\text{C},\) unless otherwise specified)

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITION</th>
<th>SYMBOL</th>
<th>VALUE</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Reverse voltage</td>
<td></td>
<td>(V_R)</td>
<td>5</td>
<td>V</td>
</tr>
<tr>
<td>Forward current</td>
<td>(I_F)</td>
<td>100 mA</td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td>Peak forward current (t_p/T = 0.5, t_p = 100 , \mu\text{s})</td>
<td>(I_{FM})</td>
<td>200 mA</td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td>Surge forward current (t_p = 100 , \mu\text{s})</td>
<td>(I_{FSM})</td>
<td>1 A</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Power dissipation</td>
<td>(P_V)</td>
<td>160 mW</td>
<td></td>
<td>mW</td>
</tr>
<tr>
<td>Junction temperature</td>
<td>(T_J)</td>
<td>100 °C</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Operating temperature range</td>
<td>(T_{\text{amb}})</td>
<td>-40 to +85 °C</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Storage temperature range</td>
<td>(T_{\text{stg}})</td>
<td>-40 to +100 °C</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Soldering temperature</td>
<td>(T_{\text{sd}})</td>
<td>260 °C</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Thermal resistance junction/ambient</td>
<td>(R_{\text{thJA}})</td>
<td>250 K/W</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

![Fig. 1 - Power Dissipation Limit vs. Ambient Temperature](image1)

![Fig. 2 - Forward Current Limit vs. Ambient Temperature](image2)

**BASIC CHARACTERISTICS** (\(T_{\text{amb}} = 25 \, ^\circ\text{C},\) unless otherwise specified)

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITION</th>
<th>SYMBOL</th>
<th>MIN.</th>
<th>TYP.</th>
<th>MAX.</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Forward voltage</td>
<td>(I_F = 100 , mA, t_p = 20 , \text{ms})</td>
<td>(V_F)</td>
<td>1.35</td>
<td>1.6</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td></td>
<td>(I_F = 1 , A, t_p = 100 , \mu\text{s})</td>
<td>(V_F)</td>
<td>2.6</td>
<td>3</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>Temperature coefficient of (V_F)</td>
<td>(I_F = 1 , mA)</td>
<td>(T_KV_F)</td>
<td>-1.8</td>
<td></td>
<td></td>
<td>mV/K</td>
</tr>
<tr>
<td>Reverse current</td>
<td>(V_R = 5 , V)</td>
<td>(I_R)</td>
<td></td>
<td>100</td>
<td></td>
<td>μA</td>
</tr>
<tr>
<td>Junction capacitance</td>
<td>(V_R = 0 , V, f = 1 , \text{MHz}, E = 0)</td>
<td>(C_i)</td>
<td>60</td>
<td></td>
<td></td>
<td>pF</td>
</tr>
<tr>
<td>Radiant intensity</td>
<td>(I_F = 100 , mA, t_p = 20 , \text{ms})</td>
<td>(I_e)</td>
<td>4</td>
<td>9.5</td>
<td>20</td>
<td>mW/sr</td>
</tr>
<tr>
<td></td>
<td>(I_F = 1 , A, t_p = 100 , \mu\text{s})</td>
<td>(I_e)</td>
<td></td>
<td>70</td>
<td></td>
<td>mW/sr</td>
</tr>
<tr>
<td>Radiant power</td>
<td>(I_F = 100 , mA, t_p = 20 , \text{ms})</td>
<td>(\Phi_e)</td>
<td>40</td>
<td></td>
<td></td>
<td>mW</td>
</tr>
<tr>
<td>Temperature coefficient of (\Phi_e)</td>
<td>(I_F = 100 , mA)</td>
<td>(T_K\Phi_e)</td>
<td>-0.6</td>
<td></td>
<td></td>
<td>%/K</td>
</tr>
<tr>
<td>Angle of half intensity</td>
<td></td>
<td>(\varphi)</td>
<td>± 60</td>
<td></td>
<td></td>
<td>deg</td>
</tr>
<tr>
<td>Peak wavelength</td>
<td>(I_F = 100 , mA)</td>
<td>(\lambda_p)</td>
<td>940</td>
<td></td>
<td></td>
<td>nm</td>
</tr>
<tr>
<td>Spectral bandwidth</td>
<td>(I_F = 100 , mA)</td>
<td>(\Delta\lambda)</td>
<td>30</td>
<td></td>
<td></td>
<td>nm</td>
</tr>
<tr>
<td>Temperature coefficient of (\lambda_p)</td>
<td>(I_F = 100 , mA)</td>
<td>(T_K\lambda_p)</td>
<td>0.2</td>
<td></td>
<td></td>
<td>nm/K</td>
</tr>
<tr>
<td>Rise time</td>
<td>(I_F = 100 , mA)</td>
<td>(t_r)</td>
<td>15</td>
<td></td>
<td></td>
<td>ns</td>
</tr>
<tr>
<td>Fall time</td>
<td>(I_F = 100 , mA)</td>
<td>(t_f)</td>
<td>15</td>
<td></td>
<td></td>
<td>ns</td>
</tr>
</tbody>
</table>
BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

Fig. 3 - Pulse Forward Current vs. Pulse Duration

Fig. 4 - Forward Current vs. Forward Voltage

Fig. 5 - Forward Voltage vs. Ambient Temperature

Fig. 6 - Radiant Intensity vs. Forward Current

Fig. 7 - Radiant Power vs. Forward Current

Fig. 8 - Relative Radiant Intensity/Power vs. Ambient Temperature
**Fig. 9 - Relative Radiant Power vs. Wavelength**

**Fig. 10 - Relative Radiant Intensity vs. Angular Displacement**

**PACKAGE DIMENSIONS** in millimeters

- **Ø2.4** ± 0.15
- **1.75 ± 0.1**
- **2.8 ± 0.15**
- **2.2**
- **0.9**
- **0.8**

Pin identification

Drawing-No.: 6.541-5067.01-4
Issue: 6; 23.09.13

**Mounting Pad Layout**

Dimensions: Reflow and vapor phase (wave soldering)
SOLDER PROFILE

Fig. 11 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:
- Floor life: 168 h
- Conditions: \( T_{\text{amb}} < 30 \, ^\circ \text{C}, \, \text{RH} < 60 \, \% \)

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label.
- Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

TAPE AND REEL

PLCC-2 components are packed in antistatic blister tape (DIN IEC (CO) 564) for automatic component insertion. Cavities of blister tape are covered with adhesive tape.

MISSING DEVICES

A maximum of 0.5 % of the total number of components per reel may be missing, exclusively missing components at the beginning and at the end of the reel. A maximum of three consecutive components may be missing, provided this gap is followed by six consecutive components.

The tape leader is at least 160 mm and is followed by a carrier tape leader with at least 40 empty compartments. The tape leader may include the carrier tape as long as the cover tape is not connected to the carrier tape. The least component is followed by a carrier tape trailer with a least 75 empty compartments and sealed with cover tape.
COVER TAPE REMOVAL FORCE

The removal force lies between 0.1 N and 1.0 N at a removal speed of 5 mm/s. In order to prevent components from popping out of the blisters, the cover tape must be pulled off at an angle of 180° with regard to the feed direction.
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